RV4C020ZP HZG

Pch -20V -2.0A Small Signal MOSFET

Datasheet

AEC-Q101 Qualified

V _{DSS}	-20V
R _{DS(on)} (Max.)	260mΩ
ا _D	±2.0A
P _D	1.5W

Features

- 1) Low on resistance.
- 2) Small high power package
- 3) Low voltage drive(1.5V)
- 4) 100% UIS tested.

Application

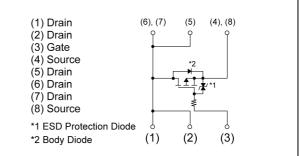
Switching circuits

High speed line driver High side load switch

5) Wettable Flank for automated optical solder inspection(AOI). Electrode part 130µm guarantee.

• Outline DFN1616-6W

Inner circuit



Packaging specifications

		Packing	Embossed Tape
		Reel size (mm)	180
	Туре	Tape width (mm)	8
	•	Quantity (pcs)	3000
		Taping code	TCR1
		Marking	ZP

• Absolute maximum ratings (T_a = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	-20	V
Continuous drain current	۱ _D *1	±2.0	Α
Pulsed drain current	I _{DP} *2	±4.0	А
Gate - Source voltage	V _{GSS}	±8	V
Avalanche current, single pulse	I _{AS} *3	2.0	А
Avalanche energy, single pulse	E _{AS} *3	0.2	mJ
Power dissipation	P _D *4	1.5	W
Junction temperature	Tj	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

•Thermal resistance

Parameter	Sumbol	Values			Linit
Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R_{thJA}^{*4}	-	-	83.4	°C/W

•Electrical characteristics (T_a = 25°C)

Deremeter	Cump of	Conditions		Values		Unit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -1mA	-20	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	-21.9	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20V, V _{GS} = 0V	-	-	-1	μA	
Gate - Source leakage current	I _{GSS}	V _{GS} = ±8V, V _{DS} = 0V	-	-	±10	μA	
Gate threshold voltage	V _{GS(th)}	V _{DS} = -10V, I _D = -1mA	-0.3	-	-1.3	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = -1mA referenced to 25°C	-	2.4	-	mV/°C	
		V _{GS} = -4.5V, I _D = -2.0A	-	180	260		
Static drain - source	D *5	V _{GS} = -2.5V, I _D = -1.0A	-	240	340	mΩ	
on - state resistance	$R_{DS(on)}^{*5}$	V _{GS} = -1.8V, I _D = -0.5A	-	360	480	11122	
		V _{GS} = -1.5V, I _D = -0.2A	-	400	560		
Forward Transfer Admittance	Y _{fs} * ⁵	V _{DS} = -10V, I _D = -2.0A	1.0	-	-	S	

*1 Vgs≦-2.5V

- *2 Pw \leq 10µs , Duty cycle \leq 1%
- *3 L \simeq 0.1mH, V_{DD} = -10V, R_G = 25 Ω , Starting T_j = 25°C Fig.3-1,3-2
- *4 Mounted on a Cu board (40mm×40mm×0.8mm)
- *5 Pulsed





• Electrical characteristics ($T_a = 25^{\circ}C$)

Deremeter	Cumphol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	V _{GS} = 0V	-	80	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	30	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	5	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq -10V, V_{GS} = -4.5V$	-	10	-	
Rise time	t _r *5	I _D = -0.5A	-	120	-	20
Turn - off delay time	t _{d(off)} *5	R _L ≃ 20Ω	-	3800	-	ns
Fall time	t _f *5	R _G = 10Ω	-	1500	-	

• Gate charge characteristics ($T_a = 25^{\circ}C$)

Deremeter	Sumbol	Conditions	Values			Unit
Parameter	Symbol	mbol Conditions		Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≃ -10V,	-	2.0	-	
Gate - Source charge	Q _{gs} *5	I _D = 0.5A,	-	0.2	-	nC
Gate - Drain charge	${\sf Q_{gd}}^{*5}$	V _{GS} = -4.5V	-	0.2	-	

•Body diode electrical characteristics (Source-Drain) ($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ _s	$T = 25^{\circ}$	-	-	-1.25	А
Pulse forward current	I_{SP}^{*2}	T _a = 25°C	-	-	-4.0	А
Forward voltage	V_{SD}^{*5}	V _{GS} = 0V, I _S = -1.25A	-	-	-1.2	V





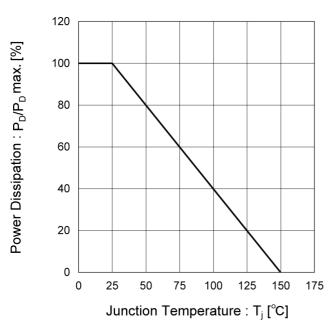


Fig.2 Maximum Safe Operating Area

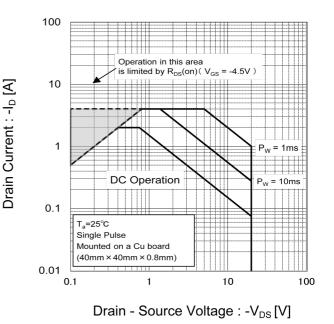
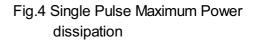
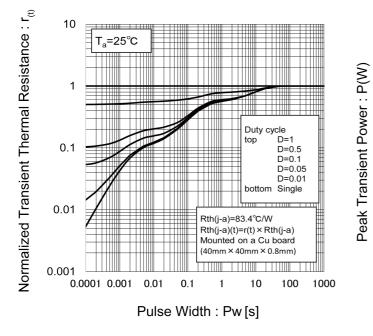
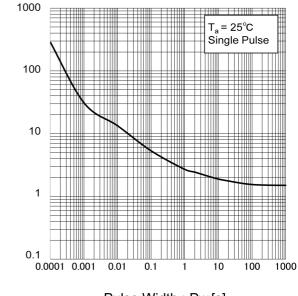


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width









• Electrical characteristic curves

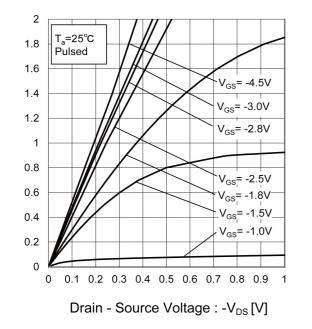


Fig.5 Typical Output Characteristics(I)

Fig.6 Typical Output Characteristics(II)

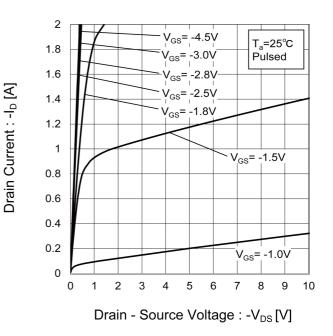


Fig.7 Breakdown Voltage vs. Junction Temperature

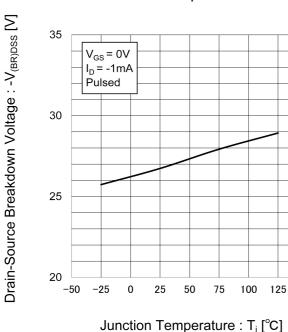
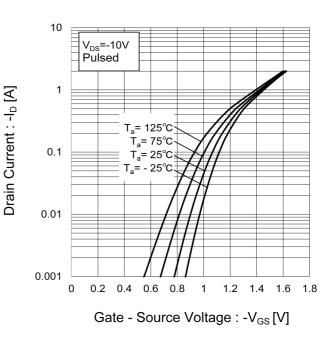


Fig.8 Typical Transfer Characteristics





150

• Electrical characteristic curves

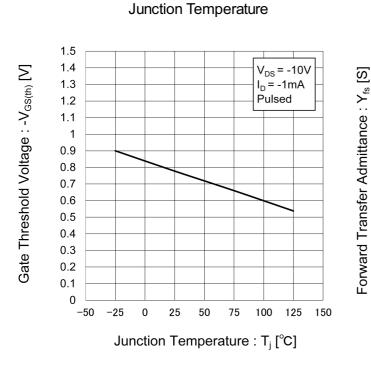


Fig.9 Gate Threshold Voltage vs.

Fig.10 Forward Transfer Admittance vs. Drain Current

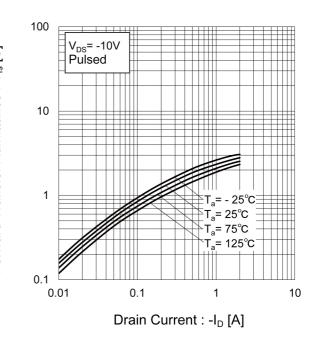
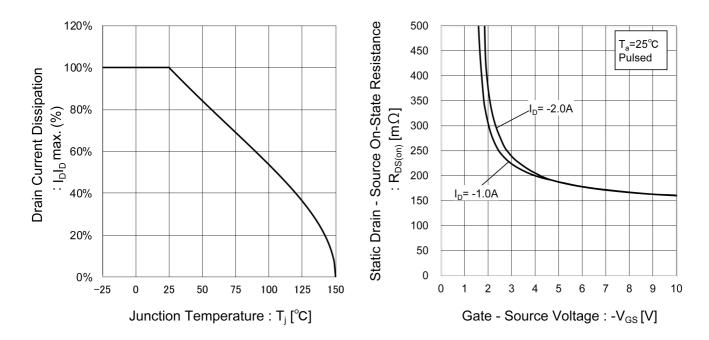


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage





-1.5V

10

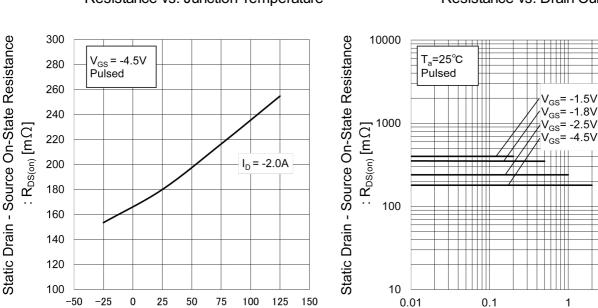


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

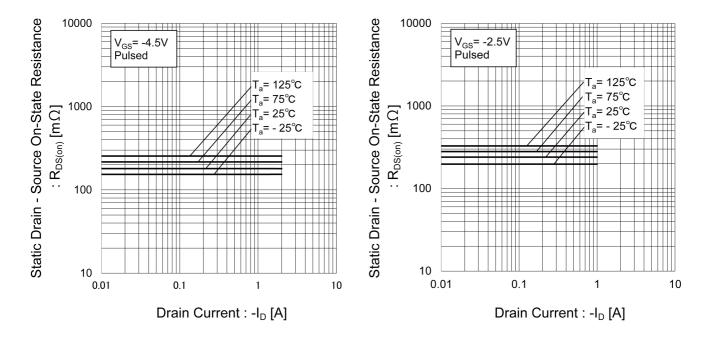
Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)



Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

Junction Temperature : T_i [°C]

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)





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• Electrical characteristic curves

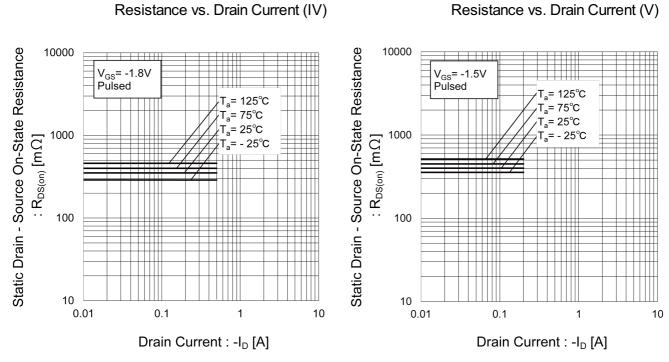


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

Fig.20 Switching Characteristics

Fig.18 Static Drain - Source On - State

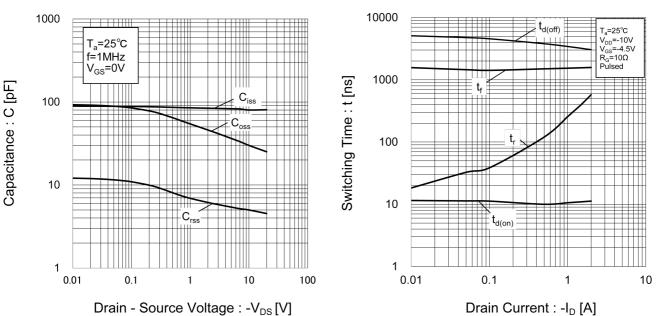
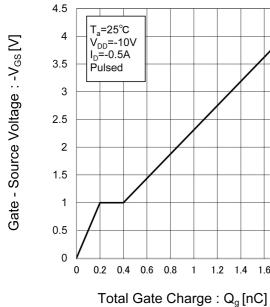


Fig.19 Typical Capacitance vs.

Drain - Source Voltage



•Electrical characteristic curves

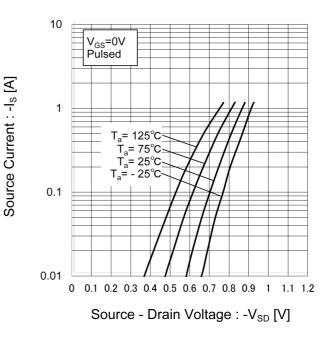




0.4 0.6 0.8 1 1.2 1.4 1.6 1.8

2

Fig.22 Source Current vs. Source Drain Voltage







Measurement circuits

Fig. 1-1 SWITCHING TIME MEASUREMENT CIRCUIT

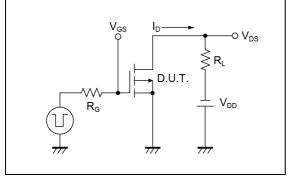


Fig. 2-1 GATE CHARGE MEASUREMENT CIRCUIT

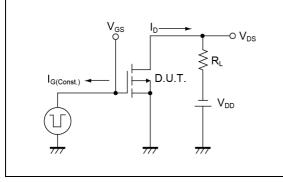


Fig.3-1 Avalanche Measurement Circuit

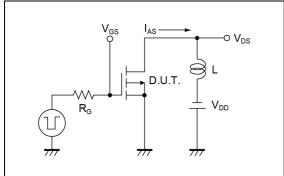


Fig. 1-2 SWITCHING WAVEFORMS

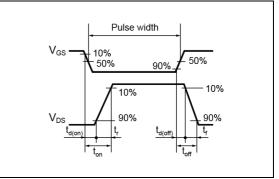


Fig. 2-2 GATE CHARGE WAVEFORM

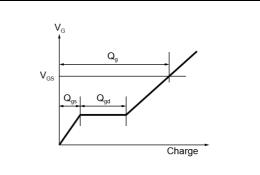
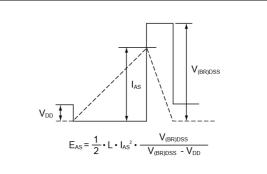


Fig.3-2 Avalanche Waveform



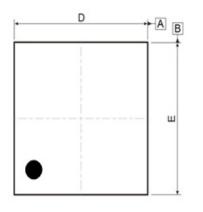
Notice

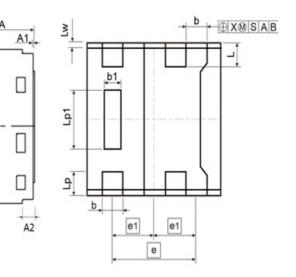
This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

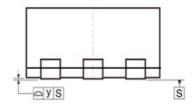


Dimensions

DFN1616-6W







DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A2	0.130	_	0.005	Ι
b	0.20	0.30	0.008	0.012
b1	0.10	0.30	0.004	0.012
D	1.50	1.70	0.059	0.067
E	1.50	1.70	0.059	0.067
е	1.00		0.0)39
e1	0.	50	0.0)20
Lp	0.20	0.30	0.008	0.012
Lp1	0.52	0.72	0.020	0.028
Lw	0.06		0.0)02
Х	-	0.10	-	0.003
Υ	-	0.10	_	0.003

Dimension in mm/inches





Notice

Precaution on using ROHM Products

 If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA
CLASSII	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSI	CLASSII	CLASSⅢ

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:

[a] Installation of protection circuits or other protective devices to improve system safety

[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
 - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

Precaution for Disposition

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